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SPECIFICATIONS										
ITEM	TEST METHOD REQUIREMENTS		QT	AT						
Resistance to soldering heat	1) Reflow soldering (To be 2 times MAX.) Peak TMP. 250 °C MAX. Reflow TMP. over 230 °C within 60 sec. Pre-heating. 150 to 200 °C 90 to 120 sec. 2) Soldering irons: 400 ± 10 °C, for 5 ± 1 sec.	No deformation of case of excessive looseness of the terminals.	×	_						
Solderability	Soldered at solder temperature, $245 \pm 3$ °C for immersion duration, $3 \pm 0.3$ sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	_						

## (note 1)

There's a case which FPC/FFC retention force doesn't fulfill the value,

because FPC/FFC specification affects the result of FPC/FFC retention force.

Note QT:Q	tualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.		ELC-391183-01-00		
HS	SPECIFICATION SHEET	PART NO.	FH75-**S-0. 5SH(01)			
	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	Δ	2/2